

2.7mil PP1080

2.9mil CORE

15mil CORE+PP

2.9mil CORE

AR-BPREG

Primary Signal Layer 1 (1 oz.cu)

L2\_GND Plane Layer 2 (1 oz.cu )

L3\_PWR Plane Layer 3 (1 oz.cu )

L4\_SIG Layer 4 (1 oz.cu )

L5\_GND Plane Layer 5 (1 oz.cu )

Solder Signal Layer 6 (1 oz.cu)

30°-45°

[ET]

[R]

[S<0.1MM ]

0.6 F 1.6MM/R 0.3+/-0.1MM

1.0 F 1.8MM/R 0.4+/-0.1MM

1.2 F 2.0MM/R 0.5+/-0.1MM

2.0 F 3.0MM/R 0.55+/-0.1MM

Impedance Control Table				
LAYER	SINGLE ENDED TRACE		DIFFERENTIAL TRACE	
	WIDTH (mil)	IMPEDANCE (OHM+/-10%)	WIDTH/SPACE (mil)	IMPEDANCE (OHM+/-10%)
1 6	4 mil	50 ohm	4.1/ 12mil	100 ohm
			4.2/ 7 mil	90 ohm
			4.5/6.5mil	85 ohm
4	5 mil	50 ohm	4.1/ 10mil	100 ohm
			4.3/7.3mil	90 ohm
			4.6/6.8mil	85 ohm

Purchase Order And Specification Sheet

Dielectric Material:

☒FR4

Total board Layers:

☒6

Board Thickness:

☒63+/-10%

Silkscreen Colors:

☒White

Soldermask Colors:

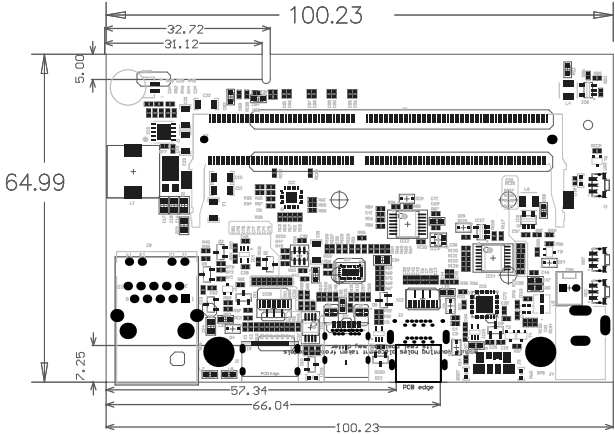
☒Green☐Red☐Yellow☐Black☐Other

Surface Finished:





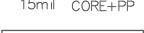




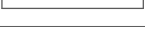
☐HASL☐OSP☐GOLDFINGER☒IMMERSION GOLD

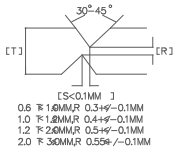
Other Notes:

1.Via:All vias need filling soldermask.  
2. Silkscreenpermanent white non-conductive epoxy inc.where appropriate clip silkscreen line width not to exceed 0.005"to ensure silkscreen clarity.  
3. Plating:solder resist over bare copper on both sides of board.



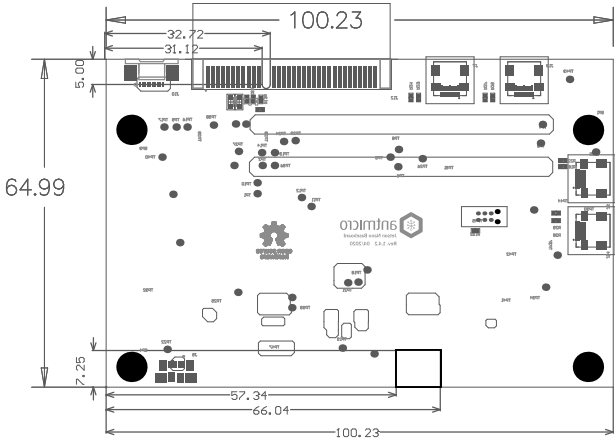
DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
+	9.84	PLATED	5
+	10.0	PLATED	834
o	15.75	PLATED	14
+	17.72	PLATED	20
□	35.04	PLATED	10
□	35.43	PLATED	6
○	40.16	PLATED	2
o	40.16	PLATED	4
o	66.93	PLATED	2
◊	145.67	PLATED	7
+	39.02	NON-PLATED	2
○	39.37	NON-PLATED	2
△	43.31	NON-PLATED	1
○	62.99	NON-PLATED	1
○	127.95	NON-PLATED	2
▫	43.3x23.62	PLATED	2
▫	47.24x23.62	PLATED	4
▫	51.18x23.62	PLATED	2
⌘	68.5x27.56	PLATED	2
⌘	92.52x35.43	PLATED	2
⌘	118.11x39.37	PLATED	1
⌘	118.11x39.37	PLATED	1
⌘	137.79x39.37	PLATED	1

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	15mil CORE+PP
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	2.9mil CORE
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	PREPREG
	Solder Signal Layer 6 (1 oz.cu)



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Dielectric Material:	<input checked="" type="checkbox"/> FR4
Total board Layers:	<input checked="" type="checkbox"/> 6
Board Thickness:	<input checked="" type="checkbox"/> 63+/-10%
Silkscreen Colors:	<input checked="" type="checkbox"/> White
Soldermask Colors:	<input checked="" type="checkbox"/> Green <input type="checkbox"/> Red <input type="checkbox"/> Yellow <input type="checkbox"/> Black <input type="checkbox"/> Other
Surface Finished:	<input type="checkbox"/> HASL <input type="checkbox"/> OSP <input type="checkbox"/> GOLDFINGER <input checked="" type="checkbox"/> IMMERSION GOLD
Other Notes:	
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